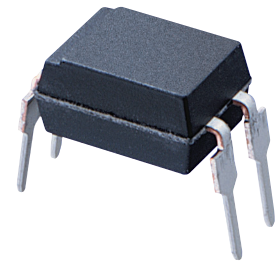
PC852XJ0000F Series PC853XJ0000F Series

DIP 4pin Darlington Phototransistor Ouput, High Collector-emitter Voltage Photocoupler



■ Description

PC852XJ0000F Series/PC853XJ0000F Series contains an IRED optically coupled to a phototransistor.

It is packaged in a 4-pin DIP, available in SMT gullwing lead-form option.

Input-output isolation voltage(rms) is 5.0kV.

Collector-emitter voltage is 350V and CTR is MIN. 1 000% at input current of 1mA.

■ Features

1. 4pin DIP package
2. Double transfer mold package (Ideal for Flow Soldering)
3. High collector-emitter voltage (V_{CEO} : 350V)
4. Durlington phototransistor output (CTR : MIN. 1 000% at I_F=1mA, V_{CE}=2V)
5. Large collector power disspation : **PC853XJ0000F** (P_C : 300mW)
6. High isolation voltage between input and output ($V_{iso(rms)}$: 5kV)
7. Lead-free and RoHS directive compliant

■ Agency approvals/Compliance

1. Recognized by UL1577, file No. E64380 (as model No. **PC852/PC853**)
2. Approved by VDE, DIN EN60747-5-2(*) (only for **PC852XJ0000F** series as an option), file No. 40008087 (as model No. **PC852**)
3. Package resin : UL flammability grade (94V-0)

(*)DIN EN60747-5-2 : successor standard of DIN VDE0884

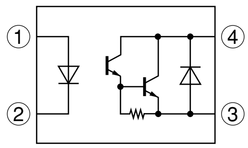
■ Applications

1. Telephone line interface/isolation
2. Interface to power supply circuit
3. Controller for SSRs, DC motors

Notice The content of data sheet is subject to change without prior notice.
In the absence of confirmation by device specification sheets, SHARP takes no responsibility for any defects that may occur in equipment using any SHARP devices shown in catalogs, data books, etc. Contact SHARP in order to obtain the latest device specification sheets before using any SHARP device.

Sheet No.: D2-A04002EN
Date Jun. 30. 2005

■ Internal Connection Diagram



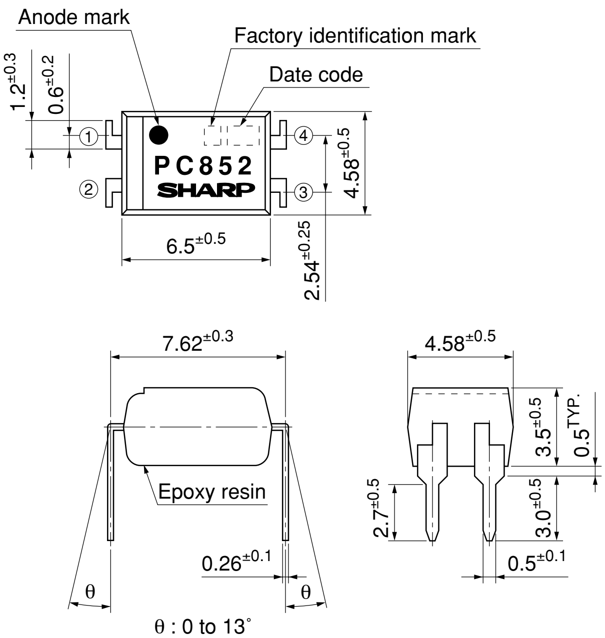
① Anode
③ Cathode
④ Emitter
⑤ Collector

■ Outline Dimensions

(Unit : mm)

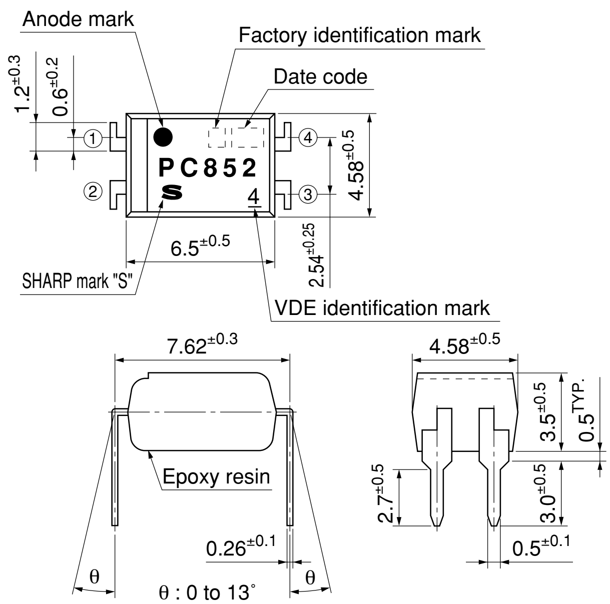
● PC852XJ0000F Series

1. Through-Hole [ex. **PC852XJ0000F**]



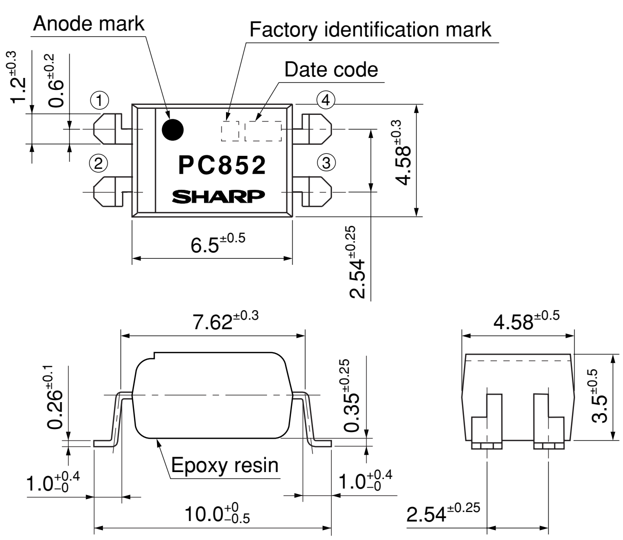
Product mass : approx. 0.23g

2. Through-Hole (VDE option) [ex. **PC852XYJ000F**]



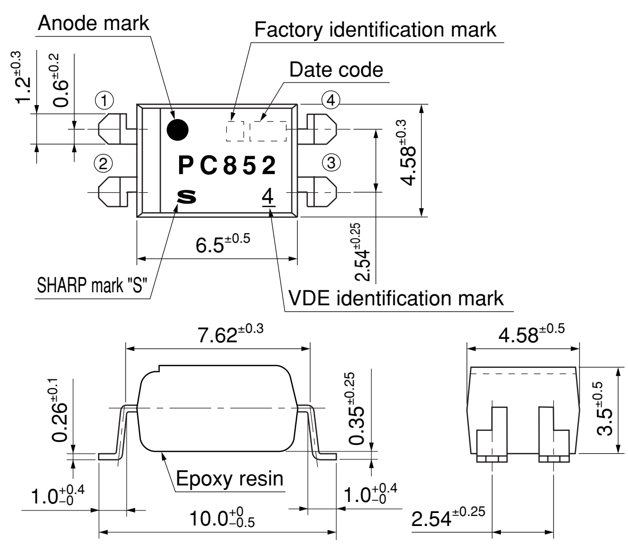
Product mass : approx. 0.23g

3. SMT Gullwing Lead-Form [ex. **PC852XIJ000F**]



Product mass : approx. 0.22g

4. SMT Gullwing Lead-Form (VDE option)
[ex. **PC852XPYJ00F**]



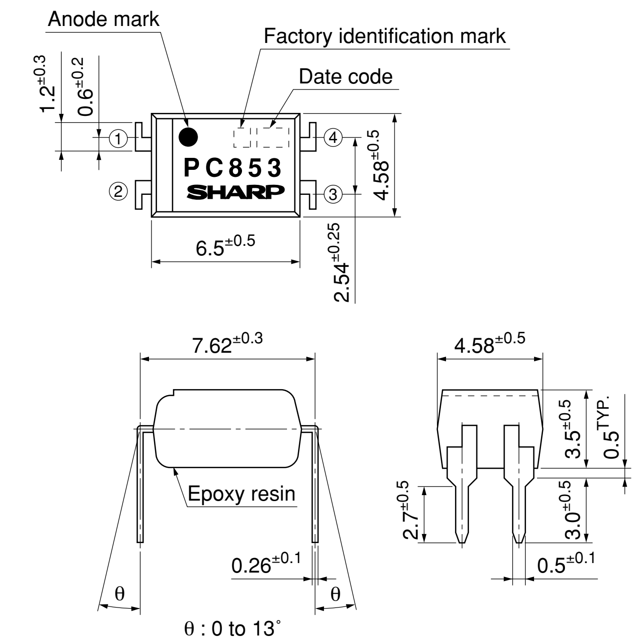
Product mass : approx. 0.22g

Plating material : SnCu (Cu : TYP. 2%)

● **PC853XJ0000F Series**

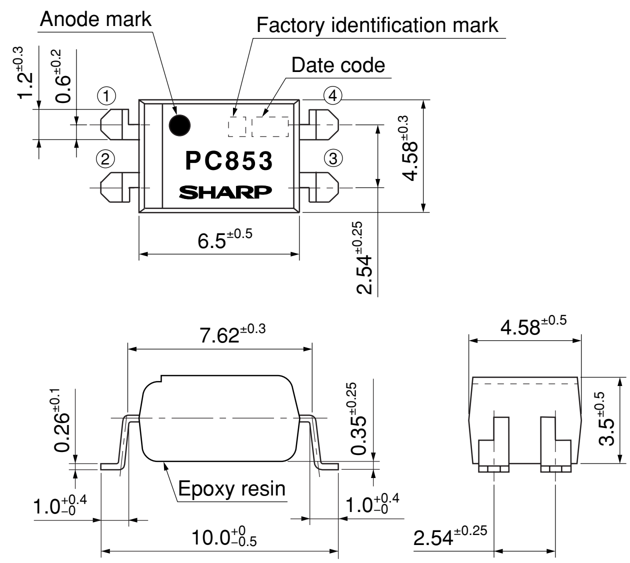
(Unit : mm)

1. Through-Hole [ex. **PC853XJ0000F**]



Product mass : approx. 0.23g

2. SMT Gullwing Lead-Form [ex. **PC853XIJ000F**]



Product mass : approx. 0.22g

Date code (2 digit)

1st digit				2nd digit	
Year of production				Month of production	
A.D.	Mark	A.D	Mark	Month	Mark
1990	A	2002	P	January	1
1991	B	2003	R	February	2
1992	C	2004	S	March	3
1993	D	2005	T	April	4
1994	E	2006	U	May	5
1995	F	2007	V	June	6
1996	H	2008	W	July	7
1997	J	2009	X	August	8
1998	K	2010	A	September	9
1999	L	2011	B	October	O
2000	M	2012	C	November	N
2001	N	⋮	⋮	December	D

repeats in a 20 year cycle

Factory identification mark

Factory identification Mark	Country of origin
no mark	Japan
■	
◢	Indonesia
◥	China

* This factory marking is for identification purpose only.
Please contact the local SHARP sales representative to see the actural status of the production.

Rank mark

There is no rank mark indicator.

■ Absolute Maximum Ratings

(T_a=25˚C)

Parameter		Symbol	Rating PC852XJ0000F	Rating PC853XJ0000F	Unit
Input	Forward current	I_F	50		mA
Input	*1 Peak forward current	I_{FM}	1		A
Input	Reverse voltage	V_R	6		V
Input	Power dissipation	P	70		mW
Output	Collector-emitter voltage	V_{CEO}	350		V
Output	Emitter-collector voltage	V_{ECO}	0.1		V
Output	Collector current	I_C	150		mA
Output	Collector power dissipation	P_C	150	300	mW
Total power dissipation		P_{tot}	200	320	mW
*2 Isolation voltage		$V_{iso\ (rms)}$	5.0		kV
Operating temperature		T_{opr}	−30 to +100		˚C
Storage temperature		T_{stg}	−55 to +125		˚C
*3 Soldering temperature		T_{sol}	260		˚C

*1 Pulse width≤100μs, Duty ratio : 0.001
*2 40 to 60%RH, AC for 1 minute, f=60Hz
*3 For 10s

■ Electro-optical Characteristics

(T_a=25˚C)

Parameter			Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input	Forward voltage		V_F	I_F=10mA	–	1.2	1.4	V
Input	Reverse voltage		I_R	V_R=4V	–	–	10	μA
Input	Terminal capacitance		C_t	V=0, f=1kHz	–	30	250	pF
Output	Collector dark current		I_{CEO}	V_{CE}=200V, I_F=0	–	–	200	nA
Output	Collector-emitter breakdown voltage		BV_{CEO}	I_C=0.1mA, I_F=0	350	–	–	V
Transfer charac-teristics	Collector current		I_C	I_F=1mA, V_{CE}=2V	10	40	150	mA
Transfer charac-teristics	Collector-emitter saturation voltage		$V_{CE\ (sat)}$	I_F=20mA, I_C=100mA	–	–	1.2	V
Transfer charac-teristics	Isolation resistance		R_{ISO}	DC500V, 40 to 60%RH	5×10^{10}	1×10^{11}	–	Ω
Transfer charac-teristics	Floating capacitance		C_f	V=0, f=1MHz	–	0.6	1.0	pF
Transfer charac-teristics	Cut-off frequency		f_C	V_{CE}=2V, I_C=20mA, R_L=100Ω, −3dB	1	7	–	kHz
Transfer charac-teristics	Response time	Rise time	t_r	V_{CE}=2V, I_C=20mA, R_L=100Ω	–	100	300	μs
Transfer charac-teristics	Response time	Fall time	t_f	V_{CE}=2V, I_C=20mA, R_L=100Ω	–	20	100	μs

■ Model Line-up

● PC852XJ0000F Series

Lead Form	Through-Hole		SMT Gullwing		
Package	Sleeve			Taping	
	100pcs/sleeve			2 000pcs/reel	
DIN EN60747-5-2	——	Approved	——	——	Approved
Model No.	**PC852XJ0000F**	**PC852XYJ000F**	**PC852XIJ000F**	**PC852XPJ000F**	**PC852XPYJ00F**

● PC853XJ0000F Series

Lead Form	Through-Hole	SMT Gullwing	
Package	Sleeve		Taping
	100pcs/sleeve		2 000pcs/reel
DIN EN60747-5-2	——	——	——
Model No.	**PC853XJ0000F**	**PC853XIJ000F**	**PC853XPJ000F**

Please contact a local SHARP sales representative to inquire about production status.

Fig.1 Forward Current vs. Ambient Temperature

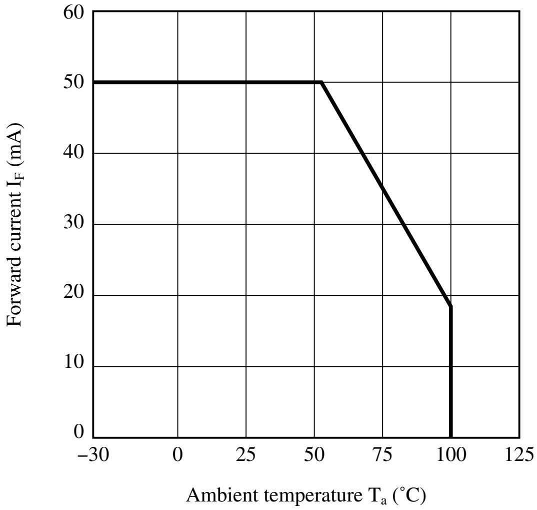


Fig.2 Diode Power Dissipation vs. Ambient Temperature

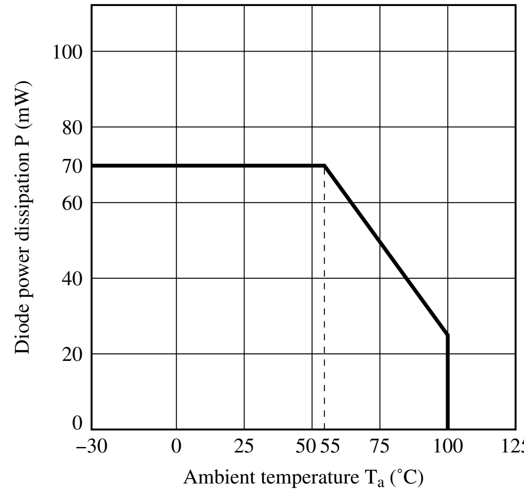


Fig.3-a Collector Power Dissipation vs. Ambient Temperature

(PC852XJ0000F)

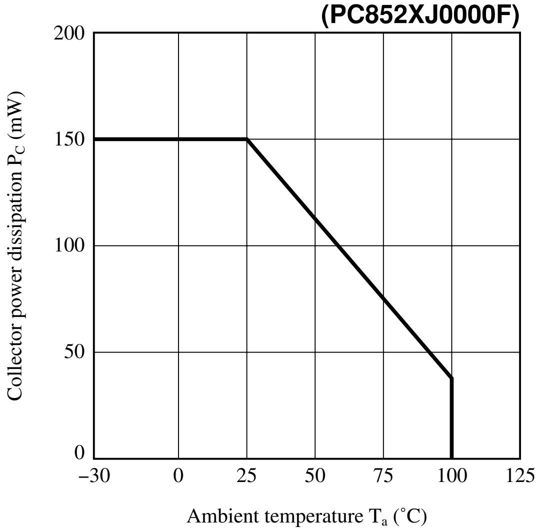


Fig.3-b Collector Power Dissipation vs. Ambient Temperature

(PC853XJ0000F)

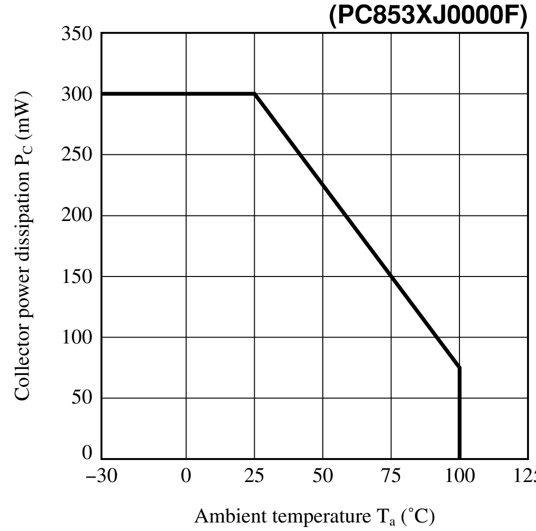


Fig.4 Total Power Dissipation vs. Ambient Temperature

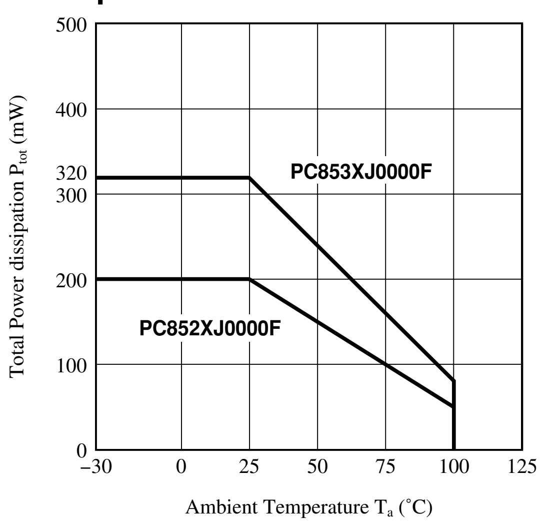


Fig.5 Peak Forward Current vs. Duty Ratio

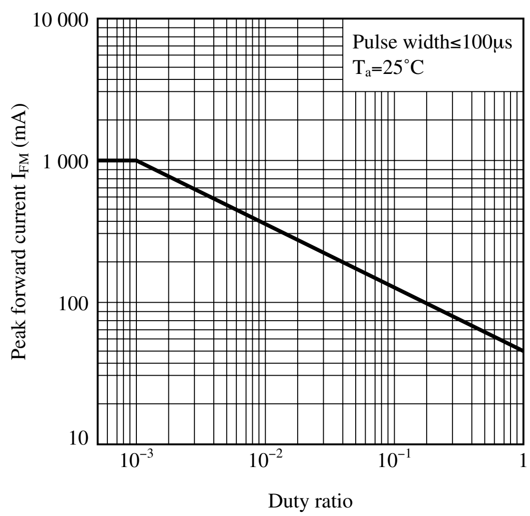


Fig.6 Forward Current vs. Forward Voltage

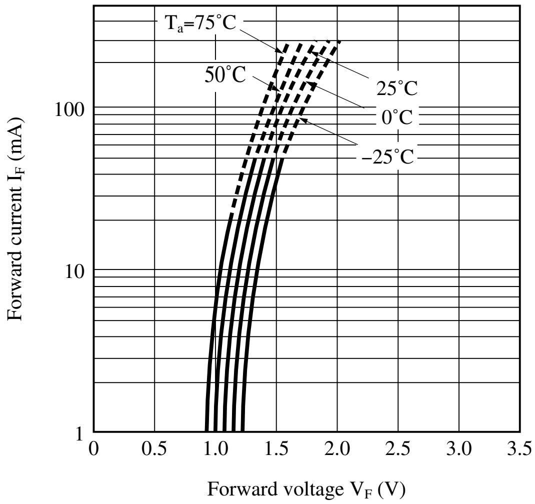


Fig.7-a Current Transfer Ratio vs. Forward Current

(PC852XJ0000F)

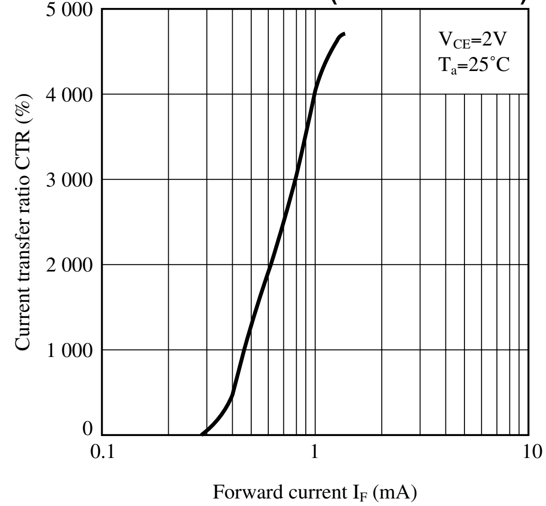


Fig.7-b Current Transfer Ratio vs. Forward Current

(PC853XJ0000F)

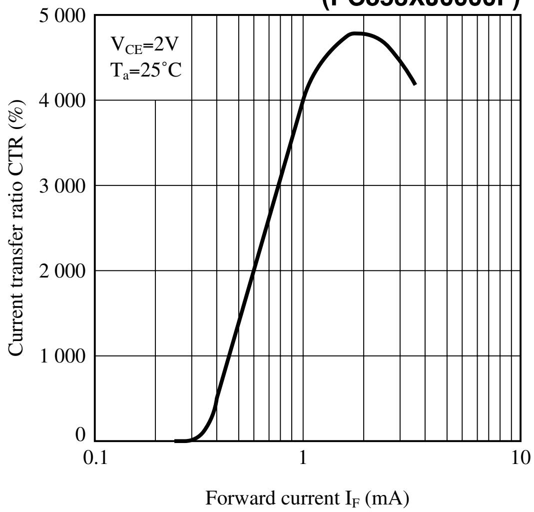


Fig.8-a Collector Current vs. Collector-emitter Voltage

(PC852XJ0000F)

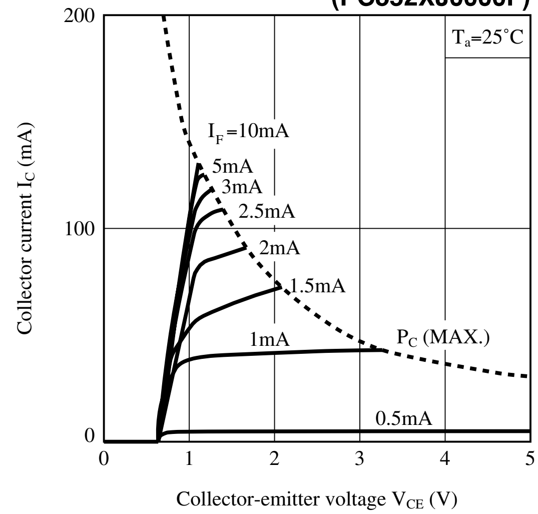


Fig.8-b Collector Current vs. Collector-emitter Voltage

(PC853XJ0000F)

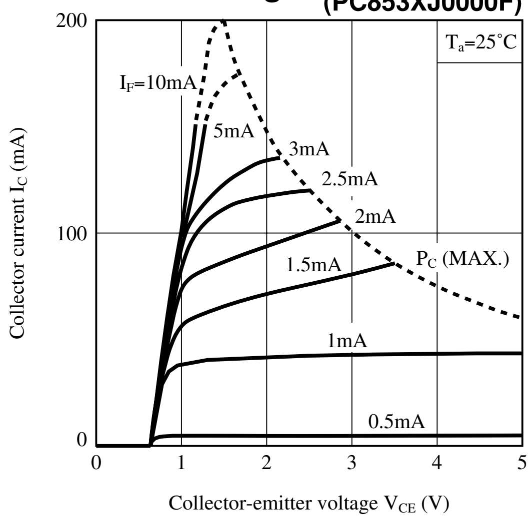


Fig.9 Relative Current Transfer Ratio vs. Ambient Temperature

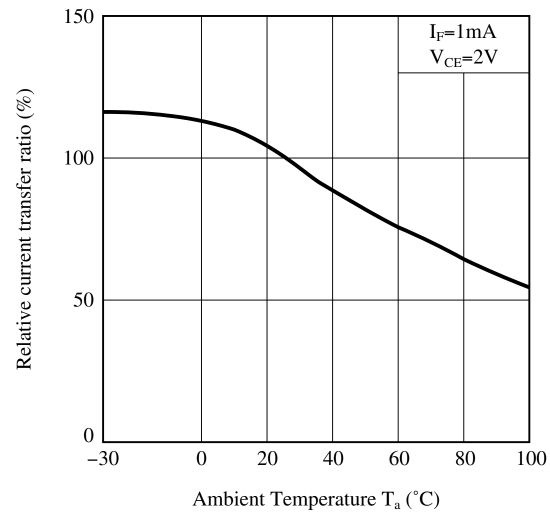


Fig.10 Collector - emitter Saturation Voltage vs. Ambient Temperature

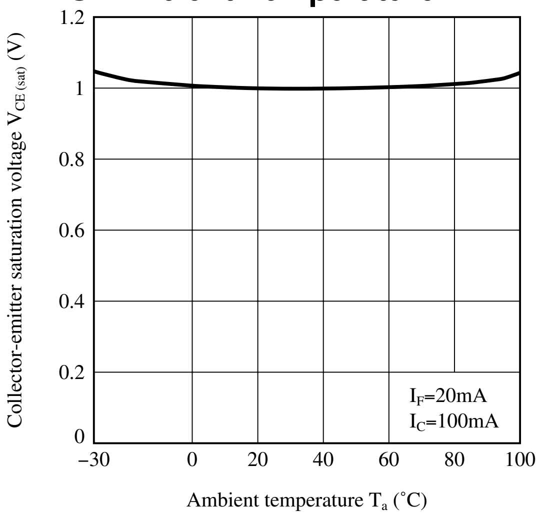


Fig.11 Collector Dark Current vs. Ambient Temperature

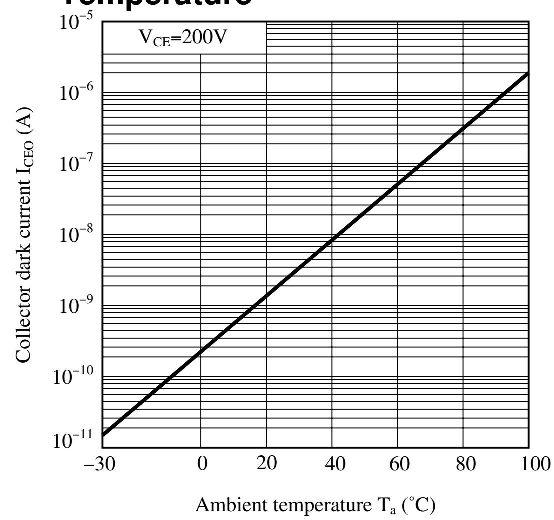


Fig.12 Response Time vs. Load Resistance

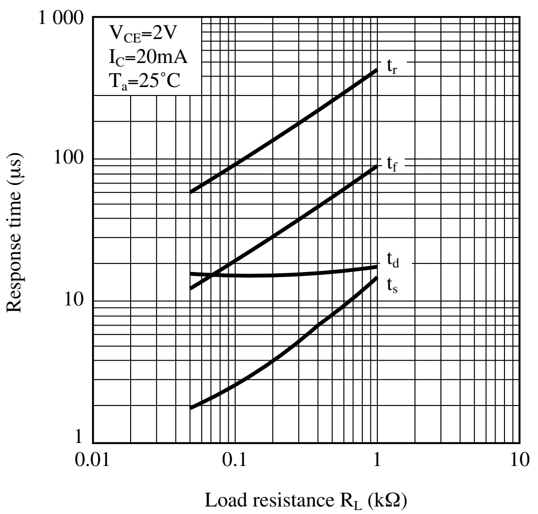
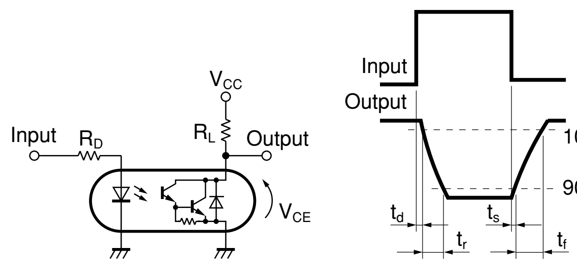


Fig.13 Test Circuit for Response Time



Please refer to the conditions in Fig.12.

Fig.14 Frequency Response

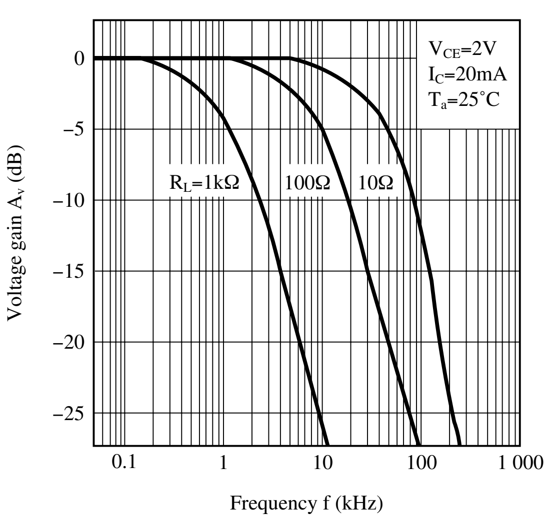
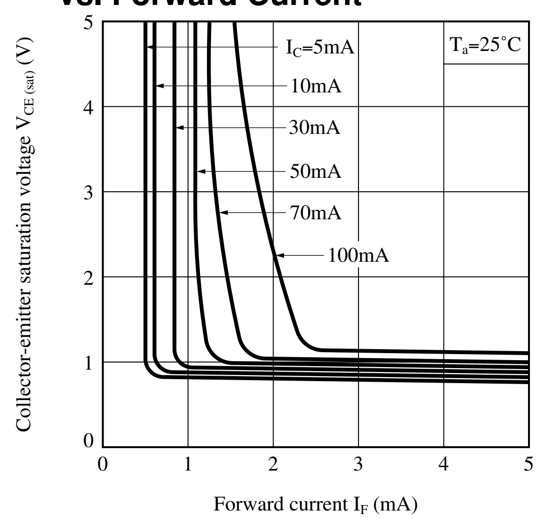


Fig.15 Collector-emitter Saturation Voltage vs. Forward Current



Remarks : Please be aware that all data in the graph are just for reference and not for guarantee.

■ Design Considerations

● Design guide

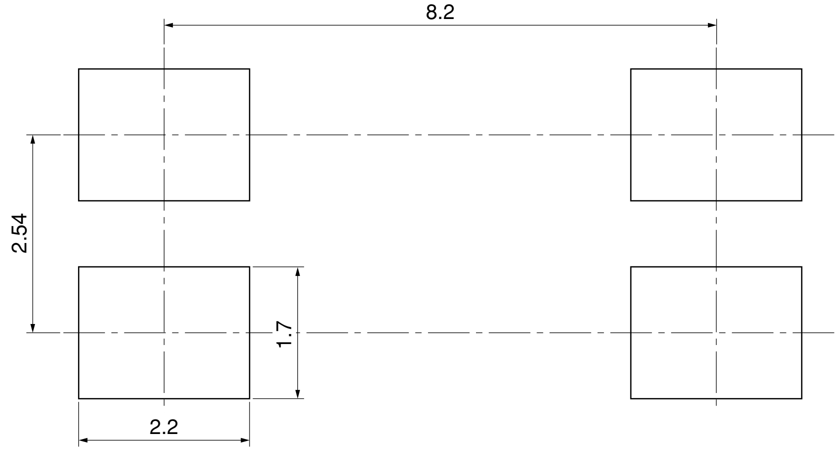
While operating at I_F<1.0mA, CTR variation may increase.
Please make design considering this fact.

This product is not designed against irradiation and incorporates non-coherent IRED.

● Degradation

In general, the emission of the IRED used in photocouplers will degrade over time.
In the case of long term operation, please take the general IRED degradation (50% degradation over 5 years) into the design consideration.

● Recommended Foot Print (reference)



(Unit : mm)

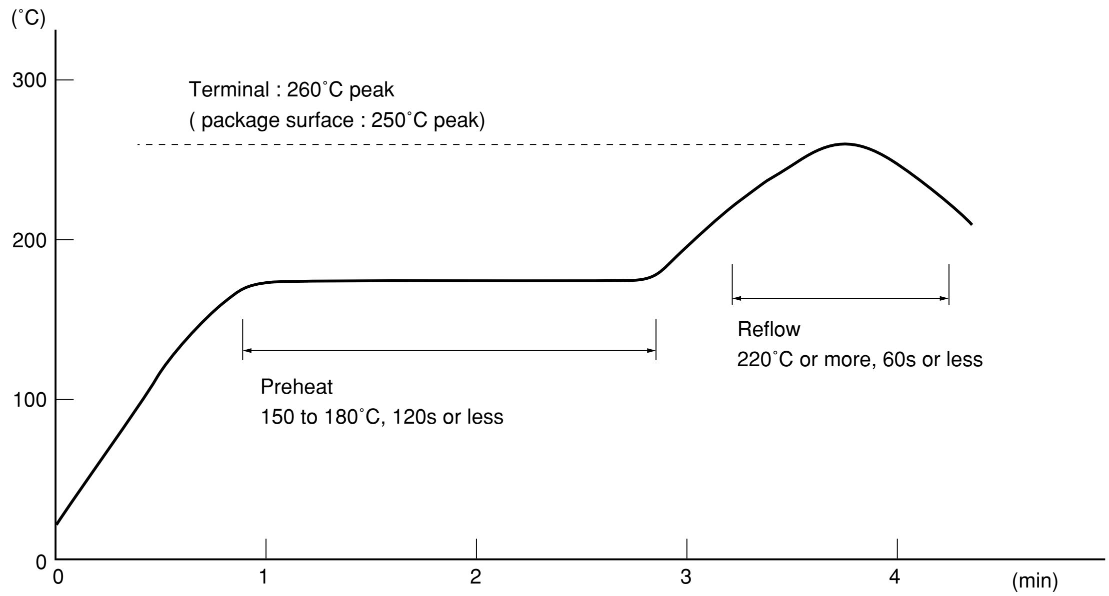
☆ For additional design assistance, please review our corresponding Optoelectronic Application Notes.

■ Manufacturing Guidelines

● Soldering Method

Reflow Soldering:

Reflow soldering should follow the temperature profile shown below.
Soldering should not exceed the curve of temperature profile and time.
Please don't solder more than twice.



Flow Soldering :

Due to SHARP's double transfer mold construction submersion in flow solder bath is allowed under the below listed guidelines.

Flow soldering should be completed below 270˚C and within 10s.
Preheating is within the bounds of 100 to 150˚C and 30 to 80s.
Please don't solder more than twice.

Hand soldering

Hand soldering should be completed within 3s when the point of solder iron is below 400˚C.
Please don't solder more than twice.

Other notices

Please test the soldering method in actual condition and make sure the soldering works fine, since the impact on the junction between the device and PCB varies depending on the tooling and soldering conditions.

● Cleaning instructions

Solvent cleaning:

Solvent temperature should be 45˚C or below Immersion time should be 3 minutes or less

Ultrasonic cleaning:

The impact on the device varies depending on the size of the cleaning bath, ultrasonic output, cleaning time, size of PCB and mounting method of the device.
Therefore, please make sure the device withstands the ultrasonic cleaning in actual conditions in advance of mass production.

Recommended solvent materials:

Ethyl alcohol, Methyl alcohol and Isopropyl alcohol
In case the other type of solvent materials are intended to be used, please make sure they work fine in actual using conditions since some materials may erode the packaging resin.

● Presence of ODC

This product shall not contain the following materials.
And they are not used in the production process for this product.
Regulation substances : CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform)

Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.

This product shall not contain the following materials banned in the RoHS Directive (2002/95/EC).

- Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBB), Polybrominated diphenyl ethers (PBDE).

■ Package specification

● Sleeve package

Package materials

Sleeve : HIPS (with anti-static material)

Stopper : Styrene-Elastomer

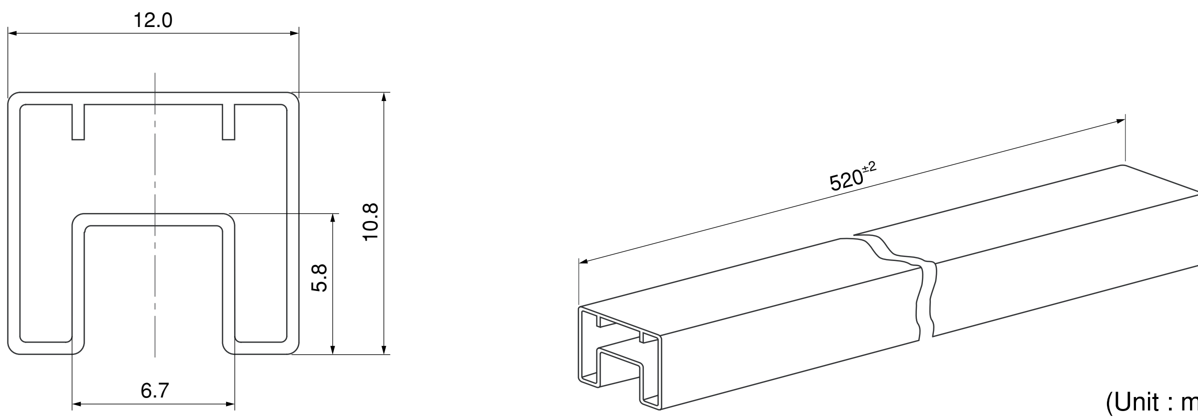
Package method

MAX. 100pcs of products shall be packaged in a sleeve. Both ends shall be closed by tabbed and tabless stoppers.

The product shall be arranged in the sleeve with its anode mark on the tabless stopper side.

MAX. 20 sleeves in one case.

Sleeve outline dimensions



(Unit : mm)

● Tape and Reel package

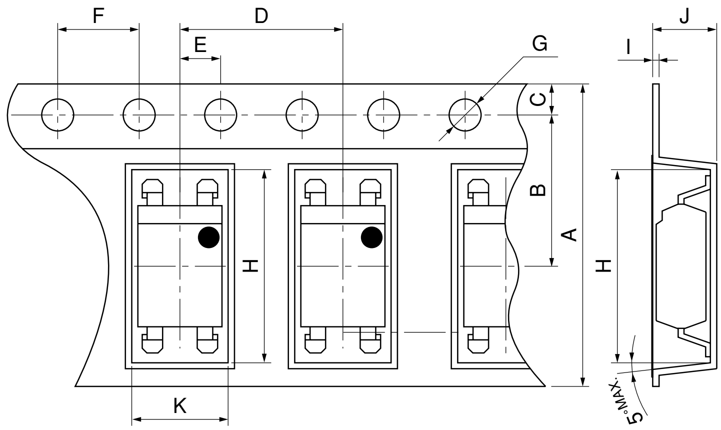
Package materials

Carrier tape : PS

Cover tape : PET (three layer system)

Reel : PS

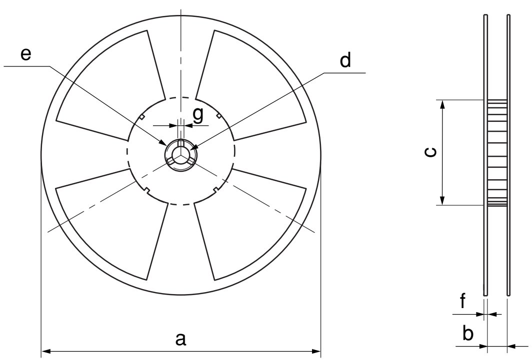
Carrier tape structure and Dimensions



Dimensions List (Unit : mm)

A	B	C	D	E	F	G
$16.0^{\pm0.3}$	$7.5^{\pm0.1}$	$1.75^{\pm0.1}$	$8.0^{\pm0.1}$	$2.0^{\pm0.1}$	$4.0^{\pm0.1}$	$\phi1.5^{+0.1}_{-0}$
H	I	J	K			
$10.4^{\pm0.1}$	$0.4^{\pm0.05}$	$4.2^{\pm0.1}$	$5.1^{\pm0.1}$			

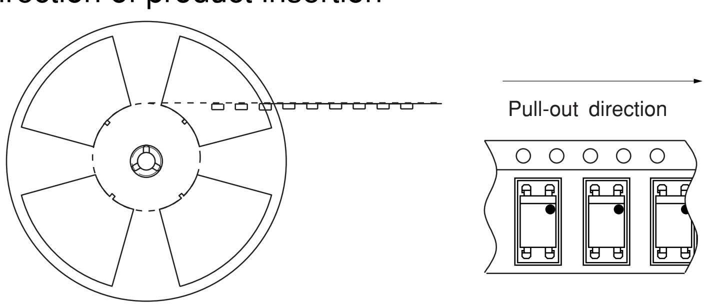
Reel structure and Dimensions



Dimensions List (Unit : mm)

a	b	c	d
330	$17.5^{\pm1.5}$	$100^{\pm1.0}$	$13^{\pm0.5}$
e	f	g	
$23^{\pm1.0}$	$2.0^{\pm0.5}$	$2.0^{\pm0.5}$	

Direction of product insertion



[Packing : 2 000pcs/reel]

■ Important Notices

· The circuit application examples in this publication are provided to explain representative applications of SHARP devices and are not intended to guarantee any circuit design or license any intellectual property rights. SHARP takes no responsibility for any problems related to any intellectual property right of a third party resulting from the use of SHARP's devices.

· Contact SHARP in order to obtain the latest device specification sheets before using any SHARP device. SHARP reserves the right to make changes in the specifications, characteristics, data, materials, structure, and other contents described herein at any time without notice in order to improve design or reliability. Manufacturing locations are also subject to change without notice.

· Observe the following points when using any devices in this publication. SHARP takes no responsibility for damage caused by improper use of the devices which does not meet the conditions and absolute maximum ratings to be used specified in the relevant specification sheet nor meet the following conditions:

(i) The devices in this publication are designed for use in general electronic equipment designs such as:

--- Personal computers
--- Office automation equipment
--- Telecommunication equipment [terminal]
--- Test and measurement equipment
--- Industrial control
--- Audio visual equipment
--- Consumer electronics

(ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection with equipment that requires higher reliability such as:

--- Transportation control and safety equipment (i.e., aircraft, trains, automobiles, etc.)
--- Traffic signals
--- Gas leakage sensor breakers
--- Alarm equipment
--- Various safety devices, etc.

(iii) SHARP devices shall not be used for or in connection with equipment that requires an extremely high level of reliability and safety such as:

--- Space applications
--- Telecommunication equipment [trunk lines]
--- Nuclear power control equipment
--- Medical and other life support equipment (e.g., scuba).

· If the SHARP devices listed in this publication fall within the scope of strategic products described in the Foreign Exchange and Foreign Trade Law of Japan, it is necessary to obtain approval to export such SHARP devices.

· Contact and consult with a SHARP representative if there are any questions about the contents of this publication.